

## Product Change Notification - GBNG-29BUCJ678

**Date:** 16 Jun 2017  
**Product Category:** 8-bit PIC Microcontrollers; 16-Bit - Microcontrollers and Digital Signal Controllers  
**Notification subject:** CCB 2687 Final Notice: Qualification of CuPdAu bond wire in selected products of the 200K and 250K wafer technologies available in 48L UQFN package at NSEB assembly site.  
**Notification text:** **PCN Status:**  
 Final notification.

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K and 250K wafer technologies available in 48L UQFN package at NSEB assembly site.

**Pre Change:**

Assembled at NSEB using gold (Au) bond wire.

**Post Change:**

Assembled at NSEB using gold (Au) or palladium coated copper with gold flash (CuPdAu) bond wire.

**Pre and Post Change Summary:**

	Pre Change	Post Change
<b>Assembly Site</b>	NSEB	NSEB
<b>Wire material</b>	Au	Au or CuPdAu
<b>Die attach material</b>	8600	8600
<b>Molding compound material</b>	G700LTD	G700LTD
<b>Lead frame material</b>	EFTEC-64T	EFTEC-64T

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire at NSEB assembly site.

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**

July 16, 2017

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

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	June 2017					-->	July 2017			
Workweek	22	23	24	25	26		27	28	29	30
Final PCN Issue Date			X							
Estimated Implementation Date									X	

**Method to Identify Change:**  
Traceability code

**Qualification Report:**  
Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report.

**Revision History:**  
**June 16, 2017:** Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN\\_GBNG-29BUCJ678\\_Qual Report.pdf](#)
  - [PCN\\_GBNG-29BUCJ678\\_Affected CPN.pdf](#)
  - [PCN\\_GBNG-29BUCJ678\\_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

<b>PCN_GBNG-29BUCJ678</b>
<b>Catalog Part Numbers</b>
PIC16F15385-E/MV
PIC16F15385-I/MV
PIC16F15385T-I/MV
PIC16F15386-E/MV
PIC16F15386-I/MV
PIC16F15386T-I/MV
PIC16LF15385-E/MV
PIC16LF15385-I/MV
PIC16LF15385T-I/MV
PIC16LF15386-E/MV
PIC16LF15386-I/MV
PIC16LF15386T-I/MV
PIC24F08KM204-I/MV
PIC24F16KA304-I/MV
PIC24F16KA304T-I/MV
PIC24F16KM204-E/MV
PIC24F16KM204-I/MV
PIC24F32KA304-E/MV
PIC24F32KA304-I/MV
PIC24F32KA304T-I/MV
PIC24FV08KM204-E/MV
PIC24FV16KA304-I/MV
PIC24FV16KM204-I/MV
PIC24FV32KA304-E/MV
PIC24FV32KA304-I/MV
PIC24FV32KA304T-I/MV